

LOCTITE ECCOBOND DAM 7010C

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PRODUCT DESCRIPTION

LOCTITE ECCOBOND DAM 7010C provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Components	One-component
Cure	Heat cure
Product Benefits	<ul style="list-style-type: none">• Crack and thermal resistant• Good chemical resistance• Low thermal expansion• High purity• Non-sag
Operating Temperature	-40 to 150°C
Application	Encapsulants, Semiconductor Encapsulant (SCE)
Typical Applications	Glob top applications, Wire bonded bare IC protection

LOCTITE ECCOBOND DAM 7010C is formulated to be used in combination with a "fill" encapsulant LOCTITE ECCOBOND FIL 7010C as a dam encapsulant. It is specially designed for glob top applications where protection of wire bonded bare IC is required.

This two material combination is also suited for the protection of multiple chips and for encapsulating components where a well-defined glob height and flat surface are required.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity @ 25 °C, mPa·s (cP):	
@ 15 s ⁻¹	80,000 to 105,000
Thixotropic Index	≥3
Density, gm/cc	1.9
Shelf Life:	
@ -40 °C, days	180
@ 25°C, day	1
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE

Recommended Cure Schedule

2 hours @ 140°C

Low Stress Cure Schedule

1 hour @ 100°C plus 1 hour @ 150°C

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Hardness, Shore D	≥90
Glass Transition Temperature(T _g), °C:	
(T _g) by DMA	130 to 140
(T _g) by TMA	135 to 145
Coefficient of Thermal Expansion, 10 ⁻⁶ /°C:	
Below T _g	14 to 18
Above T _g	60 to 65
Young's modulus (E) @ 25 °C, GPa	11
Thermal Conductivity, W/(m·K)	0.78
Extractable Ionic Content @ °C, ppm:	
Chloride (Cl ⁻)	≤10
Potassium (K ⁺)	≤10
Sodium (Na ⁺)	≤10
Ammonia (NH ₃ ⁺)	≤10
Water Absorption, %:	
24-hour boil test by weight	0.45

Electrical Properties

Volume Resistivity, ohms·cm	8.96×10 ⁺¹⁵
Surface Resistivity, ohms	5.9×10 ⁺¹⁵
Dielectric Strength, kV/mm	>20
Dielectric Constant/Dissipation Factor @ 1 MHz	3.6/0.015

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

THAWING:

1. Allow container to reach room temperature before use.
2. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
3. DO NOT re-freeze. Once thawed, the adhesive should not be re-frozen.

Directions for use

1. Cure the product per the cure schedule mentioned in the Typical Cure Schedule section of the document.
2. The surfaces on which the adhesive has to be applied should be clean, dry and free from all dust.
3. Initially dispense LOCTITE ECCOBOND DAM 7010C on the outline of the glob referred to as the "dam".
4. The dam is then filled in with LOCTITE ECCOBOND FIL 7010C material.
5. Both materials can be co-cured after dispense.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage : -40 °C

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

- (°C x 1.8) + 32 = °F
- kV/mm x 25.4 = V/mil
- mm / 25.4 = inches
- N x 0.225 = lb/F
- N/mm x 5.71 = lb/in
- psi x 145 = N/mm²
- MPa = N/mm²
- N·m x 8.851 = lb·in
- N·m x 0.738 = lb·ft
- N·mm x 0.142 = oz·in
- mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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